



Hyper-miniature Lever & Rocker Switches



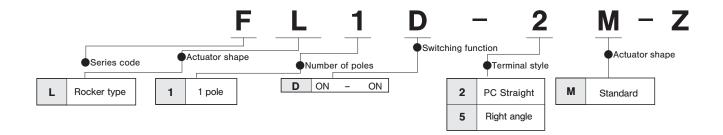
■ Features –

- 1. Hyper-miniature type. The volumetric ratio is half the conventional Series A.
- 2. Immersion cleaning is possible after soldering.
- 3. The terminal pitch is of the 0.1-inch size.
- 4. The independent detent mechanism ensures light operating feeling.
- 5. For the contact reliability, long-term stability is assured by the clip contacts.
- 6. Since the contacts are gold-plated, the switches are best suited for use in the dry circuit areas.
- 7. The full-molded type prevents malfunction caused by static electricity.

Specifications

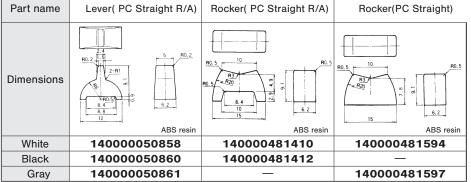
Rating	Max : 0.4 VA (28 VDC max.) Min : 1 μA 20 mVDC	
Initial contact resistance	100 mΩ max.	$(1.5~\text{mA}~200~\mu\text{VAC})$
Dielectric strength	250 VAC 1 minute	
Insulation resistance	500 MΩ min.	(250 VDC)
Electrical life	10,000 cycles at max. rating 50,000 cycles at min. rating	
Operating temperature range	-40°C∼+85°C	
Storage temperature range	-40°C∼+85°C	

■ Part Numbering

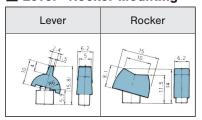


■ Standard Accessories

«Supplied separately»



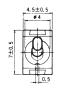
Lever •Rocker Mounting

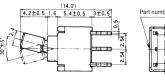


The lever and the rocker are standard accessories. Specify either of the lever or the rocker by part number.

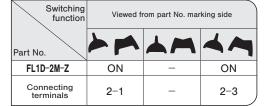












ON

2-3

Viewed from part No. marking side

ON

2-1

(Mount with Rocker)

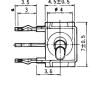
PC Straight

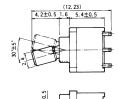
Terminal numbers are not shown on the bottom of the switch.

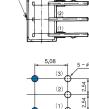
(Top view) PC Hole Layouts

SPDT

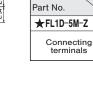








Part number marking side



Switching function

(Mount with Rocker)

R/A

Terminal numbers are not shown on the bottom of the switch. (Top view) PC Hole Layouts

Soldering	Specifications	

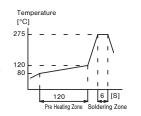
(1)Manual Soldering

Device: Soldering iron 380°C, Max.; 3 seconds, Max.

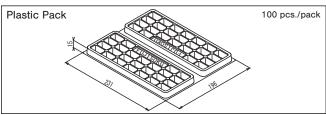
(2)Auto Soldering

Device: Jet wave type or dip type

275°C; 6 seconds, Max.



■ Packaging Specifications



Note: Mount the accessories of lever rocker after the soldering.

Flux Cleaning -

- (1)Solvents :Fluorine or Alcohol type
- (2)Cleaning after soldering should be done after the PC board is exposed to room temperature (30°C or below) for 1 to 2
- (3)Do not use ultrasonic cleaning.